

har-flex HD-CE 20 SMT hold PL1 Sample

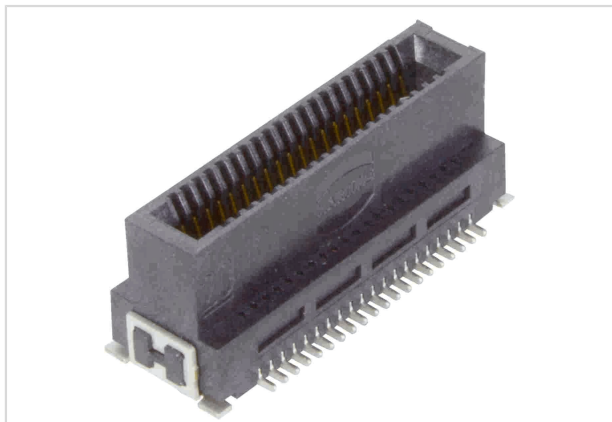


Image is for illustration purposes only. Please refer to product description.

Part number	15 03 020 2601 333
Specification	har-flex HD-CE 20 SMT hold PL1 Sample
HARTING eCatalogue	https://b2b.harting.com/15030202601333

Identification

Category	Connectors
Series	har-flex®
Identification	HD-Card Edge
Element	Connector
Features	Termination method of hold downs: SMT

Version

Termination method	Reflow soldering termination (SMT)
Connection type	Motherboard to daughtercard Mezzanine
Number of contacts	20
Pack contents	Sample

Technical characteristics

Contact rows	2
Contact spacing (termination side)	0.8 mm
Contact spacing (mating side)	0.8 mm
Data rate	25 Gbit/s
Clearance distance	≥0.2 mm Backplane ≥0.53 mm Connector ≥0.1 mm Daughtercard
Creepage distance	≥0.2 mm Backplane ≥0.53 mm Connector ≥0.1 mm Daughtercard
Limiting temperature	-55 ... +125 °C



Pushing Performance

Technical characteristics

Insertion force	≤15 N
Withdrawal force	≥4 N
Performance level	1
Mating cycles	≥200
Isolation group	IIIa (175 ≤ CTI < 400)
Moisture Sensitivity Level (MSL)	1 acc. to ECA/IPC/JEDEC J-STD-020D
Process Sensitivity Level (PSL)	R0 acc. to ECA/IPC/JEDEC J-STD-020D
Coplanarity of contacts	≤0.1 mm

Material properties

Material (insert)	Liquid crystal polymer (LCP)
Colour (insert)	Black
Material (contacts)	Copper alloy
Surface (contacts)	Au over Pd/Ni Mating side Tin plated Termination side
Material flammability class acc. to UL 94	V-0

Commercial data

Packaging size	1
Country of origin	China
eCl@ss	27460201 PCB connector (board connector)